

DESCRIPTION

The MXB050N08 uses deep trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. It can be used in a wide variety of applications.

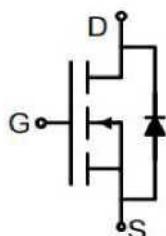
GENERAL FEATURES

- $V_{DS}=85V$, $I_D=120A$
- $R_{DS(ON)}(\text{Typ.})=4.4m\Omega$ @ $V_{GS}=10V$
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

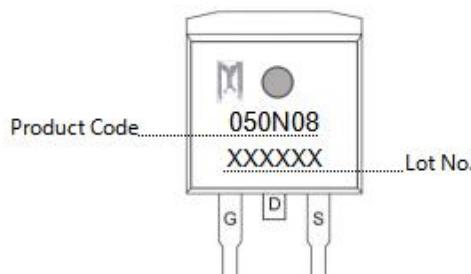
APPLICATION

- Battery management
- Load switch
- PWM applications

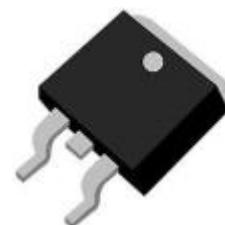
PINOUT



Schematic diagram



Marking and pin Assignment



TO-263 top view

ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MXB050N08	-55°C to 175°C	TO-263	-

ABSOLUTE MAXIMUM RATINGS ($T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	85	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	120	A
Drain Current-Continuous($T_c=100^\circ C$)	I_D	80	A
Pulsed Drain Current ^(Note1)	I_{DM}	360	A
Maximum Power Dissipation	P_D	180	W
Avalanche Energy($L=0.5mH$)	E_{AS}	780	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	°C

THERMAL RESISTANCE

Thermal Resistance, Junction-to-Case ^(Note2)	$R_{\theta JC}$	0.83	°C/W
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Note 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2.Surface Mounted on FR4 Board, $t \leq 10$ sec.


ELECTRICAL CHARACTERISTICS($T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
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Off Characteristics

Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	85	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=80\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA

On Characteristics^(Note3)

Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2.4	3.0	3.8	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=50\text{A}$	3.4	4.4	5.4	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}}=5\text{V}, I_{\text{D}} =40\text{A}$	-	75	-	S

Dynamic Characteristics^(Note4)

Input Capacitance	C_{iss}	$V_{\text{DS}}=42.5\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	3900	-	PF
Output Capacitance	C_{oss}		-	650	-	PF
Reverse Transfer Capacitance ^(Note4)	C_{rss}		-	20	-	PF
Gate Resistance	R_g	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	2	-	Ω

Switching Characteristics

Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=40\text{V}, I_{\text{D}}=10\text{A}, R_L=1\Omega, V_{\text{GS}}=10\text{V}, R_G=3\Omega$	-	14	-	nS
Turn-on Rise Time	t_r		-	23	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	36	-	nS
Turn-Off Fall Time	t_f		-	16	-	nS
Total Gate Charge	Q_g	$V_{\text{DS}}=40\text{V}, I_{\text{D}}=50\text{A}, V_{\text{GS}}=10\text{V}$	-	44	-	nC
Gate-Source Charge	Q_{gs}		-	14	-	nC
Gate-Drain Charge	Q_{gd}		-	11	-	nC

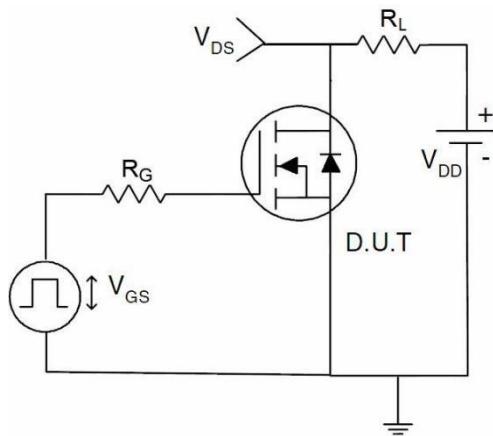
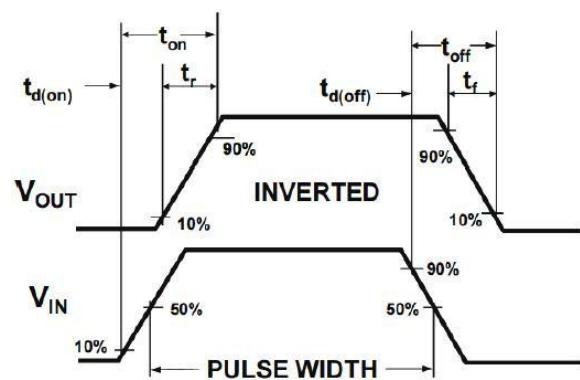
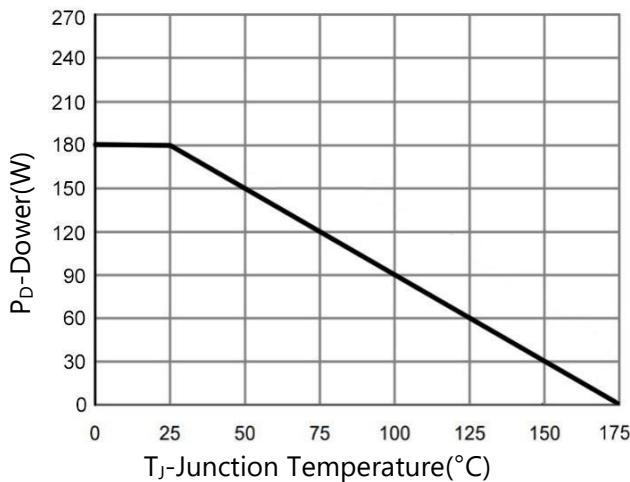
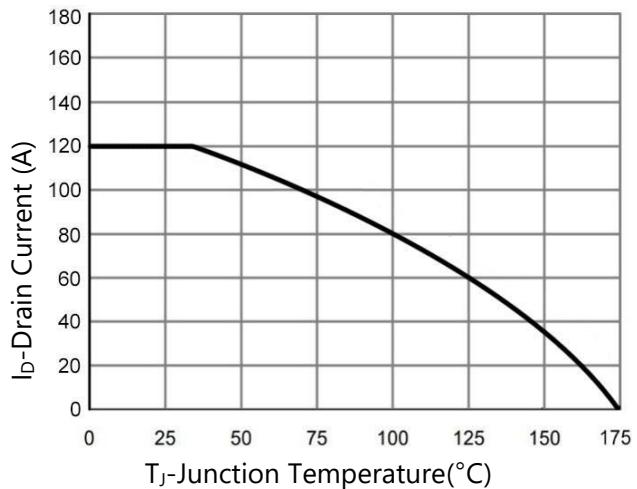
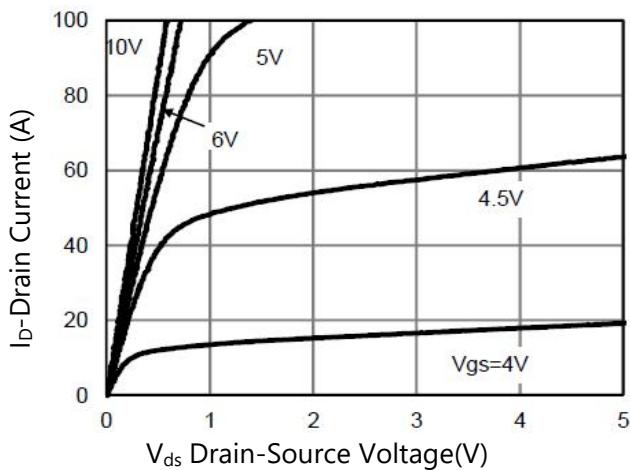
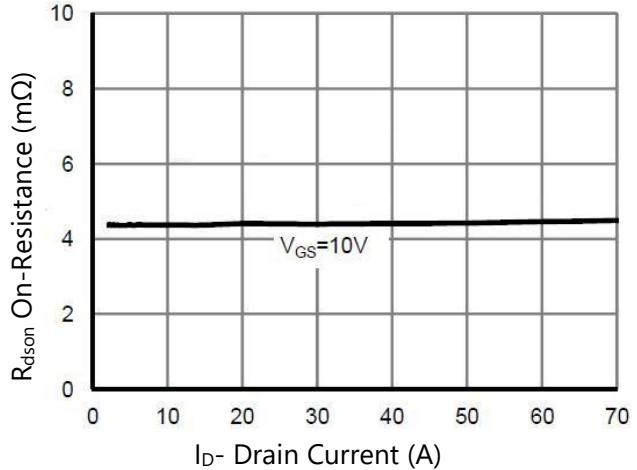
Drain-Source Diode Characteristics

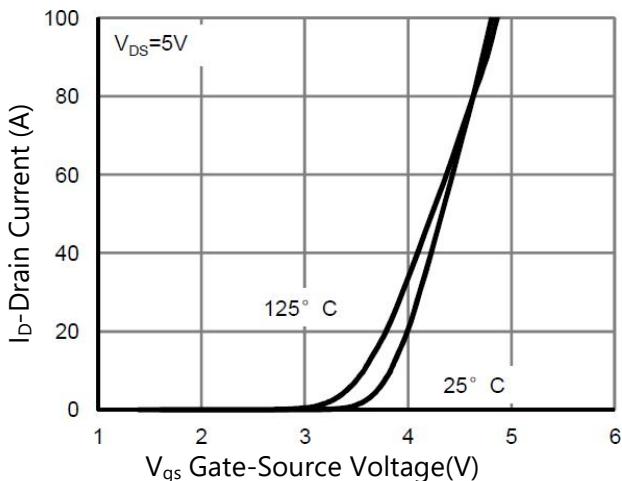
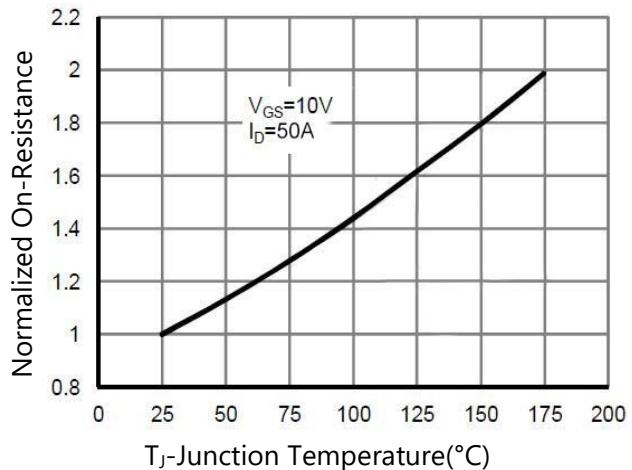
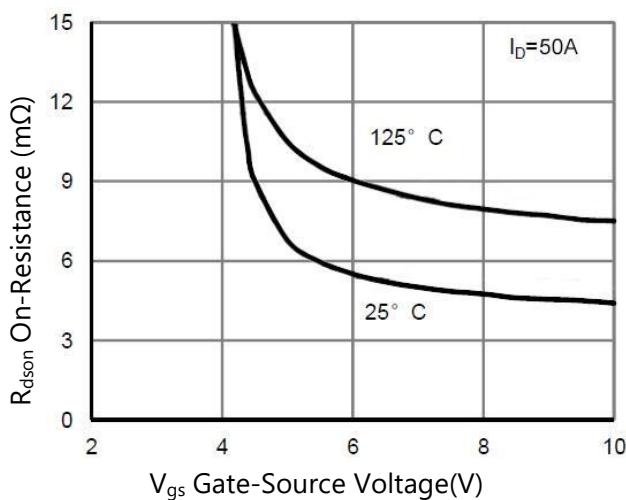
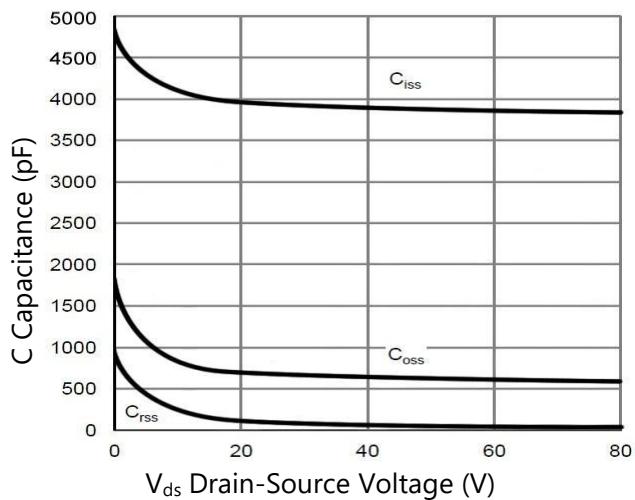
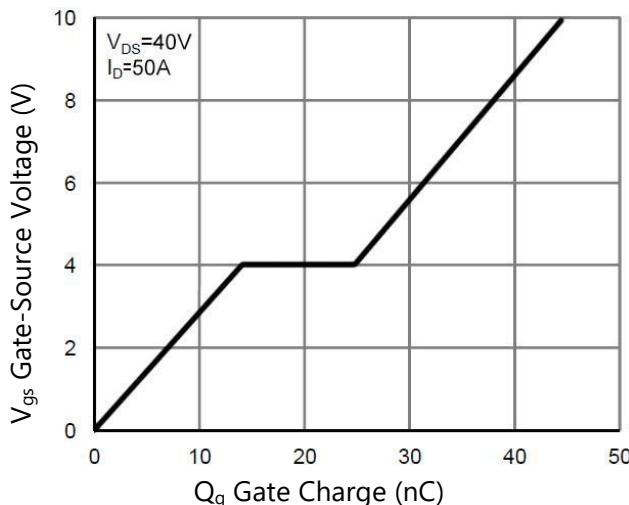
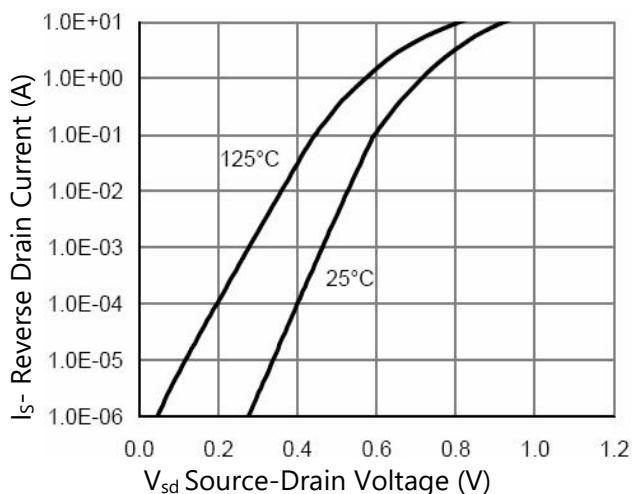
Diode Forward Voltage ^(Note3)	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{s}}=10\text{A}$	-	-	1.2	V
Diode Forward Current ^(Note2)	I_{s}		-	-	90	A

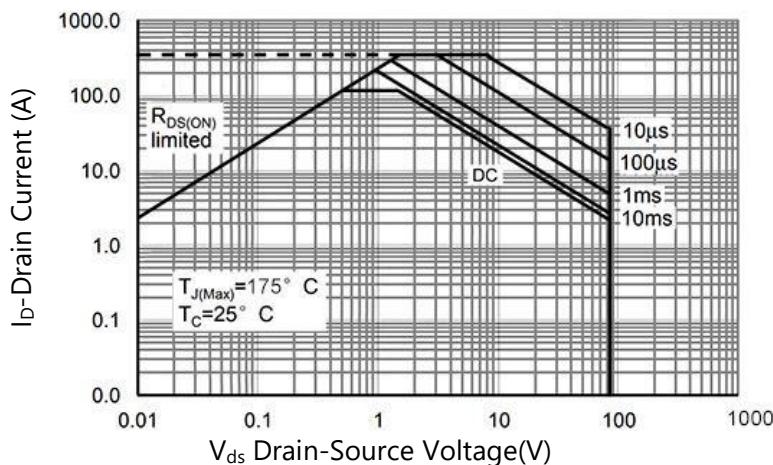
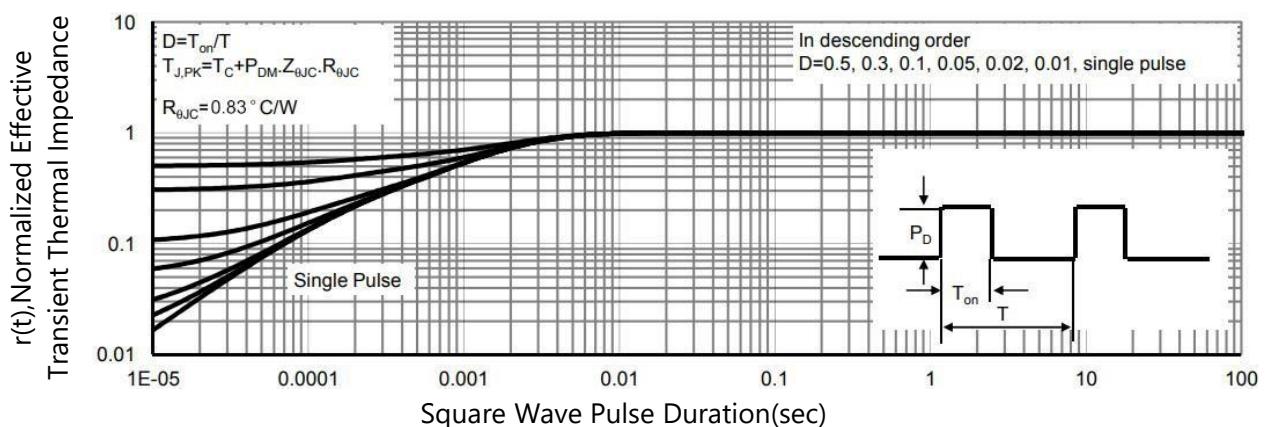
Note 2. Surface Mounted on FR4 Board, $t \leq 10\text{sec}$.

Note 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$

Note 4. Guaranteed by design, not subject to product.

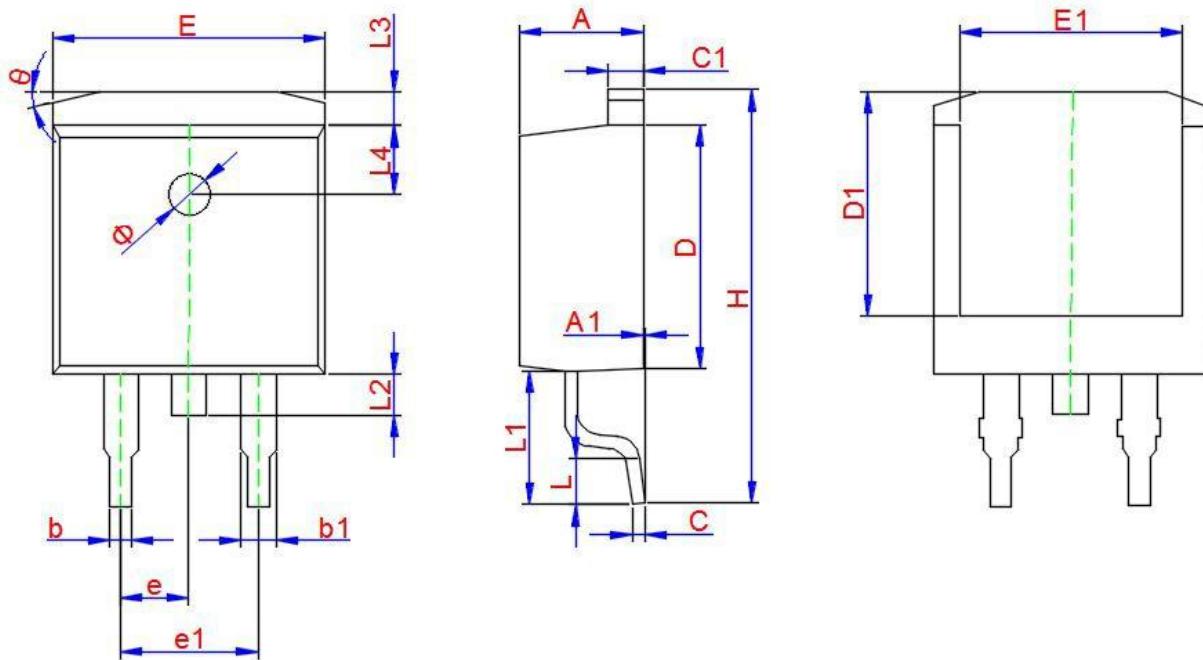

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
Figure1. Switching Test Circuit

Figure2. Switching Waveform

Figure3. Power De-rating

Figure4. Drain Current

Figure5. Output Characteristics

Figure6. R_{dson} vs Drain Current



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
Figure7. Transfer Characteristics

Figure8. R_{dson} vs Junction Temperature

Figure9. R_{dson} vs V_{gs}

Figure10. Capacitance vs V_{ds}

Figure11. Gate Charge

Figure12. Source-Drain Diode Forward



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
Figure13. Safe Operation Area

Figure14. Normalized Maximum Transient Thermal Impedance


PACKAGE INFORMATION

TO-263



Symbol	Dimensions In Millimeters		
	Min.	Typ.	Max.
A	4.30	4.50	4.70
A1	0.00	-	0.25
b	0.70	0.80	0.90
b1	1.20	1.30	1.40
c	0.40	0.47	0.55
c1	1.25	1.30	1.35
D	9.00	9.10	9.20
D1	8.00	8.10	8.20
H	14.90	15.20	15.50
E	9.80	10.00	10.20
E1	7.85	8.00	815
e1	4.93	5.08	5.23
L	2.00	2.20	2.45
L1	4.60	4.80	5.00
L2	1.30	1.50	1.70
L3	1.15	1.25	1.35
L4	2.40	2.50	2.60
Φ	-	1.5	-
e	-	2.54	-
θ	-	13°	-